Product End-of-Life Disassembly Instructions

Product Category: Monitors and Displays

Marketing Name / Model
[List multiple models if applicable.]

HP LE2001w Widescreen LCD Monitor

Name / Model #3
Name / Model #4
Name / Model #5

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

### 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm PWB-1296, PWB1251</td>
<td>2</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>N/A</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>2 Lamps</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>N/A</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>N/A</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>The part C805 and T801 on PWB-1251(Power module)</td>
<td>2</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>Power cord, VGA cable,</td>
<td>2</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td>Heeseng</td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants</td>
<td></td>
<td>N/A</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>N/A</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>N/A</td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td>N/A</td>
</tr>
</tbody>
</table>
Components, parts and materials containing radioactive substances | N/A

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>cruciform screw driver</td>
<td>5.5mm</td>
</tr>
<tr>
<td>Hex driver socket type</td>
<td>5 mm</td>
</tr>
<tr>
<td>cruciform screw driver</td>
<td>3 mm</td>
</tr>
<tr>
<td>cruciform screw driver(LGD Description #5)</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove the screws(4 pcs) on hinge to remove base assy.
2. Remove the screw(4 pcs) on back cover and then remove bucket, panel and chassis
3. Remove buttons and lens
4. Separate panel and chassis
5. Remove the VGA screw(2 pcs) on bucket
6. Remove screw(6 pcs) to take 2 boards out
7. Remove Neck Assembly by push slot on bottom of base
8. Remove screw(4 pcs) and rubber(7 pcs) on bottom of base

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
Step 1: Unfix the Screw (3 Points)
Remove the cover shield

Step 2: Dismantle the case top (down)

Step 3: Dismantle the case top (Left/right)

Step 4: Separate case top (push the case top because of damages on COF)

Step 5: Separate board ass'y

Step 6: Separate wires from the tape (2 Points)
Step 7: Pull lamp housing with tool & hands
(*Be careful not to break the Lamp)

Step 8: Pull lamp housing with hands normal to LCM

Step 9: Separated lamp ass'y (UP)
The Disassembly Procedure

LE2001w Disassembly Diagram
1. Remove screws (4 pcs).
2. Remove Base assembly.
3. Remove screws (4 pcs).
4. Remove Bucket.
5. Remove Panel and Chassis.
6. Remove Buttons and Lens.
7. Separate Panel and Chassis.
8. Remove Screws (2 pcs).
9. Remove Screws (6 pcs).
10. Remove Main Board and Power Board.
11. Remove Neck Assembly.
12. Remove Screws (4 pcs) and Rubber (7 pcs).
13. Remove Bracket.
14. Remove Screws (3 pcs).
15. Remove VESA Bracket and Hinge Cover.
16. Remove ARM BACK.
17. Remove Screws (4 pcs).
18. Remove Hinge Assembly.